

## **LISTING OF THE CLAIMS**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Previously Presented) A method for processing a plurality of leadframe items to form an integrated circuit package, each of the leadframe items comprising an integrated circuit carried by a suitable leadframe, the leadframe items being of two or more types, the method comprising the steps of:

receiving each of the leadframe items along a respective input path;

moving a plurality of holders corresponding in number to the number of integrated circuits to be processed alternately between a processing region and a respective leadframe item reception position on a respective input path such that each of the holders moves to the processing region at a time when the other of the holders moves to its respective reception position;

transferring the leadframe items from their respective input paths to respective ones of the holders at the respective reception positions;

delivering the leadframe items to the processing region; and

at the processing region, sending the leadframe items for encapsulation.

2. (Previously Presented) The method according to claim 1 in which the plurality of holders are portions of a single member, the step of moving the holders being a motion of the member.

3. (Previously Presented) The method according to claim 2, in which the motion is a reciprocating motion and the processing region is located between the at least two reception positions.

4. (Previously Presented) The method according to claim 3 in which the at least two reception positions are respectively above and below the processing region.

5. (Previously Presented) The method according to claim 1 in which the leadframe items are provided in corresponding magazines, the holders receiving the leadframe items within the corresponding magazines, and the method further including extracting the leadframe items from the magazines in the processing region.

6. (Canceled)

7. (Canceled)